Thermal Conductive Adhesive

Features:
1. Silicone-based material that combines strong adhesion with reliable thermal and electrical insulation for effective heat transfer.
2. Delivers stable performance and durability under long-term high temperatures.

Applications:
LED lighting, communication equipment, power devices

Model	Thermal Conductivity W/m·K	Tack-Free Time, at 25℃, min	Full Cure Time, at 25℃, hrs	Bonding Strength, Mpa	Hardness, Shore A	Operating Temp., ℃
JSTIV-800-10	1.0	5~10	24	≥ 1.5	40~60	-50~200
JSTIV-800-12	2.0	5~10	24	≥ 1.5	40~60	-50~200
JSTIV-800-15	3.0	5~10	24	≥ 1.5	40~60	-50~200
JSTIV-800-20	4.0	5~10	24	≥ 1.5	40~60	-50~200